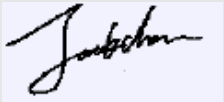
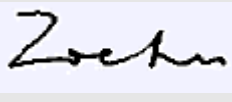




RoHS Verification Assessment Report For Products

Product	Rice cooker		
Name and address of the applicant	NEW NANFANG ELETRICAL APPLIANCE CO., LTD		
	NO.18, SHUANGGANG ROAD, CHIKAN DISTRICT, ZHANJIANG, GUANGDONG, CHINA		
Name and address of the factory	NEW NANFANG ELETRICAL APPLIANCE CO., LTD		
	NO.18, SHUANGGANG ROAD, CHIKAN DISTRICT, ZHANJIANG, GUANGDONG, CHINA		
Rating and principal characteristics	220-240V~, 50/60Hz		
Trade mark (If any)	NEW NANFANG ELETRICAL APPLIANCE CO., LTD		
Model/type	RC-XXXX, MRC-XXX, LED-XXX, MRCD-XXXX, RCD-XXXX, (The "X" can be numerical or alphabet)		
Serial no	--		
Results	Some components and parts of the above product has been evaluated and found to comply with the RoHS directive.		
Tested according to:	IEC62321:2008, IEC62321-5:2013, IEC62321-4:2013, IEC62321-6:2015		
Directive	Based on the review of previous reports and verification results of the submitted samples, the results of Cadmium, Lead, Mercury, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) comply with the limits as set by RoHS Directive 2011/65/EU.		
Name and address of the testing laboratory	Nemko Shanghai Ltd. 7 Floor No.1 Building, No.2007 Hongmei Road, Xuhui District, Shanghai, China		
Tested by			
	Signature	Date	
	Jack Chen	2016-06-02	
Verified by			
	Signature	Date	
	Zoe Lu	2016-06-02	

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1	Test case verdicts Test item does meet the requirement.....: P(ass) Test item does not meet the requirement.....: F(ail) The following models are covered by this report. Model Overview RC-XXXX, MRC-XXX, LED-XXX,MRCD-XXXX,RCD-XXXX						
2	Main Assemblies of the product						
2.1	Provide a brief description	Tests are done on the RC-10 and RCD-10 as representative for the whole models.					
3	Documents provided						
3.1	Describe briefly what kind of documents has been provided (e.g. test reports, certificates, BOM etc.)	The documentation submitted consists of RoHS declarations. In addition an exploded drawing has been submitted.					
		Form of evidence of compliance					
4	Part Description	RoHS Declaration	Material Declaration	Test report / Certificate	Screening	Remarks	Verdicts
4.1	White upper cover				X		P
4.2	silver metal				X		P
4.3	Glass				X		P
4.5	white steaming basket				X		P
4.6	silver metal pot				X		P
4.7	silver metal cover of magnetic button				X		P
4.8	silver metal body of magnetic button				X		P
4.9	silver metal enclosure of magnetic button				X		P
4.10	spring magnetic button				X		P
4.11	golden metal magnetic button				X		P

4.12	black magnet magnetic button				X		P
4.13	silver heating plate				X		P
4.14	metal heating tube				X		P
4.15	white ceramic				X		P
4.16	silver metal of middle pot				X		P
4.17	black coating of middle pot				X		P
4.18	PCB board				X		P
4.19	brown resistor body with multi-colour ring				X		P
4.20	silver pin of resistor				X		P
4.21	transparent glass body of light				X		P
4.22	silver pin of light				X		P
4.23	transparent water cup				X		P
4.24	silver metal enclosure of rice cooker				X		P
4.25	white painting of enclosure				X		P
4.26	blue painting of enclosure				X		P
4.27	white plastic panel				X		P
4.28	paper with adhesive on the panel				X		P
4.29	white plastic button				X		P
4.30	white plastic bottom cover				X		P
4.31	black plastic of socket				X		P
4.32	silver pin of socket				X		P
4.33	black plug material				X		P

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4.34	silver pin of plug				X		P
4.35	black bracket				X		P
4.36	silver contact of plug				X		P
4.37	black cord				X		P
4.38	blue wire coating				X		P
4.39	brown wire coating				X		P
4.40	yellow green wire coating				X		P
4.41	copper wire				X		P
4.42	black plastic enclosure				X		P
4.43	black bracket				X		P
4.44	golden metal contact				X		P
4.45	white glassfibre tube				X		P
4.46	blue glassfibre tube				X		P
4.47	brown glassfibre tube				X		P
4.48	yellow-green glassfibre tube				X		P
4.49	silver metal wire				X		P
4.50	black heat-shrinkable tube				X		P
4.51	copper wire				X		P
4.52	screw 1				X		P
4.53	screw 2				X		P
4.54	screw 3				X		P
4.55	screw 4				X		P

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4.56	screw 5				X		P
4.57	screw 6				X		P
4.58	silver bolt				X		P
4.59	yellow plastic washer				X		P
4.60	spring washer				X		P
4.61	white ceramic				X		P
4.62	copper strip				X		P
4.63	silver contact point				X		P
4.64	white pancake turner				X		P
4.65	transparent rice cup				X		P
4.66	Micro-switch enclosure				X		P
4.67	Copper material of Micro-switch				X		P
4.68	Panel film				X		P
4.69	Current fuse body				X		P
4.70	Current fuse metal pin				X		P
4.71	Varistor body				X		P
4.72	Varistor metal pin				X		P
4.73	Diode body				X		P
4.74	Diode metal pin				X		P
4.75	Triode body				X		P
4.76	Triode metal pin				X		P
4.78	Capacitor body				X		P

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4.79	Capacitor metal pin				X		P
4.80	Triacs body				X		P
4.81	Triacs metal pin				X		P
4.82	Connector plastic body				X		P
4.83	Connector metal pin				X		P
4.85	Relay body				X		P
4.86	Relay metal pin				X		P
4.87	X capacitor body				X		P
4.88	X capacitor metal pin				X		P
4.89	Transformer bobbin				X		P
4.90	Transformer core				X		P
4.91	Transformer tape				X		P
4.92	Transformer winding				X		P
4.93	Red tubing				X		P
4.94	Copper wire of Teflon wire				X		P
4.95	Insulation material of Teflon wire				X		P
4.96	IC enclosure				X		P
4.97	IC metal pin				X		P
4.98	Soldering tin				X		P
4.99	Standby switch body				X		P
4.100	LED body				X		P
4.101	LED metal pin				X		P

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4.102	Alarm body				X		P
4.103	Alarm metal pin				X		P
4.104	Thermal fuse body				X		P
4.105	Thermal fuse metal pin				X		P
4.106	Silicon rubber				X		P
4.107	Mica Plate				X		P
4.108	LED display body				X		P
4.109	Cover spring				X		P
4.110	silver paper				X		P
4.111	Ceramic capacitor body				X		P
4.112	Ceramic capacitor metal pin				X		P
4.113	NTC body				X		P
4.114	NTC metal pin				X		P
4.115	Transparent silicon				X		P
4.116	Black Plastic enclosure				X		P

5	Exclusions	—
	The product evaluated makes use of the indicated exemptions to the RoHS directive as published in Directive 2011/65/EU, Decision 2005/717/EC, Decision 2005/747/EC Decision 2006/310/EC, Decision 2006/690/EC, Decision 2006/691/EC, Decision 2006/692/EC, Decision 2008/385/EC, Judgment of the court (Grand Chamber) -1 April 2008- Annulment of Exemption of Deca-BDE (9a. Deca – BDE in polymeric applications.), Decision 2009/428/EC, Decision 2009/443/EC and Decision 2010/122/EU.	—
	Exemptions:	App lied
	1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.	—
	2. Mercury in straight fluorescent lamps for general purposes not exceeding: — Halophosphate 10 mg — Triphosphate with normal lifetime 5 mg — Triphosphate with long lifetime 8 mg.	—
	3. Mercury in straight fluorescent lamps for special purposes.	—
	4. Mercury in other lamps not specifically mentioned in this Annex.	—
	5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.	—
	6. Lead as an alloying element in steel containing up to 0,35 % lead by weight, aluminium containing up to 0,4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.	—
	7. Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead), — lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications, — lead in electronic ceramic parts (e.g. piezoelectric devices).	—
	8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC) amending Directive 76/769/EEC) relating to restrictions on the marketing and use of certain dangerous substances and preparations.	—
	9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.	—
	10. Lead in lead-bronze bearing shells and bushes.	—
	11. Lead used in compliant pin connector systems.	—
	12. Lead as a coating material for the thermal conduction module c-ring.	—
	13. Lead and cadmium in optical and filter glass.	—
	14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight.	—
	15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.	—
	16. Lead in linear incandescent lamps with silicate coated tubes.	—
	17. Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications.	—
	18. Lead as activator in the fluorescent powder (1% lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb) as well as when used as speciality lamps for diazo-printing reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr, Ba) 2MgSi2O7:Pb).	—
	19. Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL).	—

	20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCD).		—
	21. Lead and cadmium in printing inks for the application of enamels on borosilicate glass.		—
	22. Lead as impurity in RIG (rare earth iron garnet) Faraday rotators used for fibre optic communication systems until 31 December 2009.		—
	23. Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with NiFe lead frames and lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with copper lead frames.		—
	24. Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors.		—
	25. Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements; notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit and frit ring as well as in print pastes.		—
	26. Lead oxide in the glass envelope of Black Light Blue (BLB) lamps.		—
	27. Lead alloys as solder for transducers used in high-powered (designated to operate for several hours at acoustic power levels of 125 dB SPL and above) loudspeakers.		—
	28. Hexavalent chromium in corrosion preventive coatings of unpainted metal sheetings and fasteners used for corrosion protection and Electromagnetic Interference Shielding in equipment falling under category three of Directive 2002/96/EC (IT and telecommunications equipment). Exemption granted until 1 July 2007.		—
	29. Lead bound in crystal glass as defined in Annex I (Categories 1, 2, 3 and 4) of Council Directive 69/493/EEC.		—
	30. Cadmium alloys as electrical/mechanical solder joints to electrical conductors located directly on the voice coil in transducers used in high-powered loudspeakers with sound pressure levels of 100dBx(A) and more.		—
	31. Lead in soldering materials in mercury free flat fluorescent lamps (which e.g. are used for liquid crystal displays, design or industrial lighting).		—
	32. Lead oxide in seal frit used for making window assemblies for Argon and Krypton laser tubes.		—
	33. Lead in solders for the soldering of thin copper wires of 100 µm diameter and less in power transformers.		—
	34. Lead in cermet-based trimmer potentiometer elements.		—
	35. Cadmium in photoresistors for optocouplers applied in professional audio equipment until 31 December 2009.		—
	36. Mercury used as a cathode sputtering inhibitor in DC plasma displays with a content up to 30 mg per display until 1 July 2010.		—
	37. Lead in the plating layer of high voltage diodes on the basis of a zinc borate glass body.		—
	38. Cadmium and cadmium oxide in thick film pastes used on aluminium bonded beryllium oxide.		—
	39. Cadmium in colour-converting II-VI LEDs (< 10 µg Cd per mm ² of light-emitting area) for use in solid state illumination or display systems until 1 July 2014.		—
6	List of Used Equipment		—
	XRF	Horiba XGT-1000WR	—

7	Evaluation Approach	—
	The submitted test reports and material declarations of the single material and components used in the product are evaluated and afterwards - components and materials deemed critical are screened based on any methods described in IEC 62321:2008. For material and components where no declaration or test report is available an initial screening is performed and additional verification testing if required. Evidence of compliance of all components, materials and parts is therefore either be provided by material declarations, test reports, testing and or screening.	—
8	Compliance of Production	—
	The test report only applies to products with identical material composition as the evaluated sample. Compliance of manufacturing must be ensured by the manufacturer by implementing a incoming materials inspection procedure. Alternative components or material provided by other suppliers must be submitted to Nemko for evaluation and approval.	—

Photograph of sample

Front view



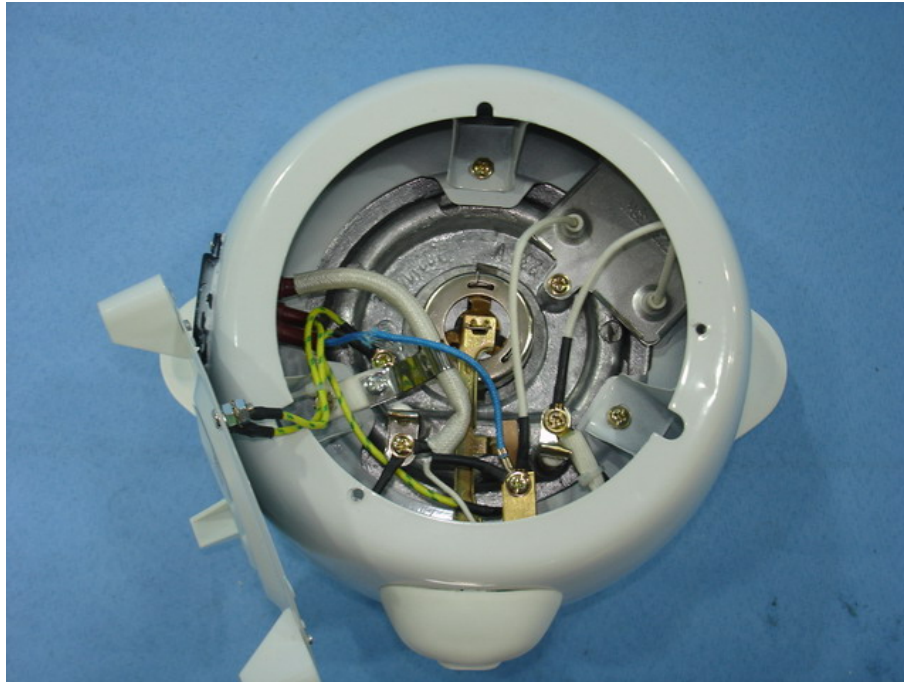
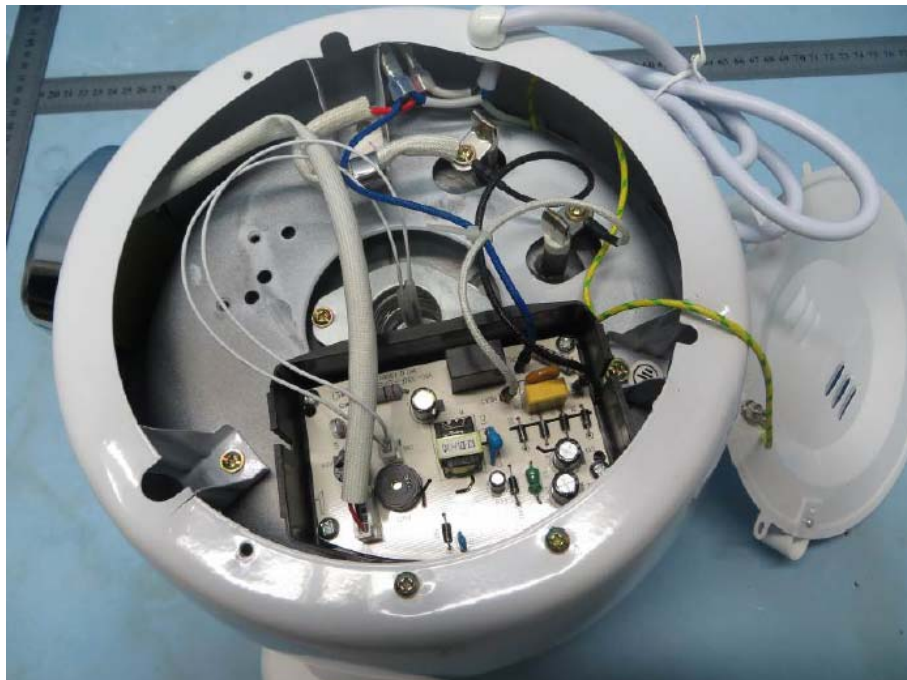
Front view



Front view

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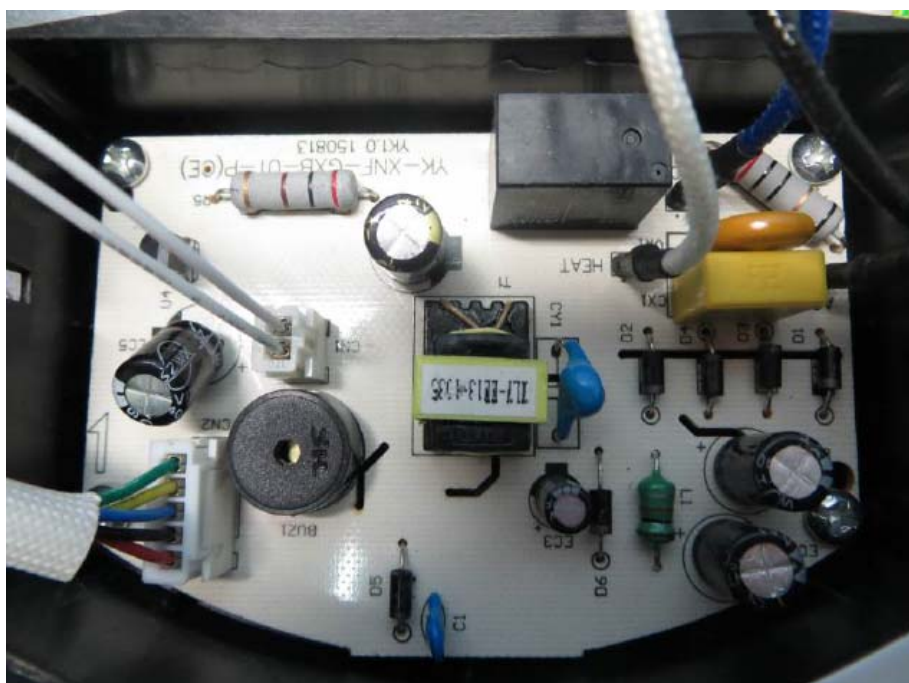
**Front view**

Internal view**Internal view**

Internal view



Internal view



Internal view

